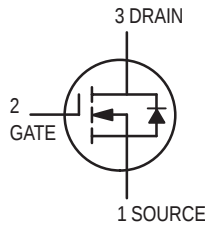
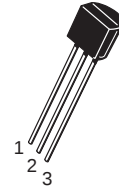


TMOS FET Transistor

N-Channel — Enhancement



VN0610LL



CASE 29-04, STYLE 22
TO-92 (TO-226AA)

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain–Source Voltage	V_{DS}	60	Vdc
Drain–Gate Voltage ($R_{GS} = 1\text{ M}\Omega$)	V_{DGR}	60	Vdc
Gate–Source Voltage	V_{GS}	± 20	Vdc
– Continuous	V_{GSM}	± 40	Vpk
– Non-repetitive ($t_p \leq 50\text{ }\mu\text{s}$)			
Drain Current	I_D	190	mAdc
Continuous	I_{DM}	1000	
Pulsed			
Total Power Dissipation @ $T_A = 25^\circ\text{C}$	P_D	400	mW
Derate above 25°C		3.2	mW/ $^\circ\text{C}$
Operating and Storage Temperature Range	T_J, T_{stg}	-55 to $+150$	$^\circ\text{C}$

THERMAL CHARACTERISTICS

Characteristics	Symbol	Max	Unit
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	312.5	$^\circ\text{C}/\text{W}$
Maximum Lead Temperature for Soldering Purposes, 1/16" from case for 10 seconds	T_L	300	$^\circ\text{C}$

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
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OFF CHARACTERISTICS

Drain–Source Breakdown Voltage ($V_{GS} = 0, I_D = 100\text{ }\mu\text{A}$)	$V_{(BR)DS}$	60	—	Vdc
Zero Gate Voltage Drain Current ($V_{DS} = 48\text{ Vdc}, V_{GS} = 0$) ($V_{DS} = 48\text{ Vdc}, V_{GS} = 0, T_J = 125^\circ\text{C}$)	I_{DSS}	—	10 500	μAdc
Gate–Body Leakage Current, Forward ($V_{GSF} = 30\text{ V}, V_{DS} = 0$)	I_{GSSF}	—	–100	nAdc

ON CHARACTERISTICS(1)

Gate Threshold Voltage ($V_{DS} = V_{GS}, I_D = 1.0\text{ mA}$)	$V_{GS(th)}$	0.8	2.5	Vdc
Static Drain–Source On–Resistance ($V_{GS} = 10\text{ V}, I_D = 500\text{ mA}$) ($V_{GS} = 10\text{ V}, I_D = 500\text{ mA}, T_C = 125^\circ\text{C}$)	$r_{DS(on)}$	—	5.0 9.0	Ω
Drain–Source On–Voltage ($V_{GS} = 5.0\text{ V}, I_D = 200\text{ mA}$) ($V_{GS} = 10\text{ V}, I_D = 500\text{ mA}$)	$V_{DS(on)}$	—	1.5 2.5	Vdc
On–State Drain Current ($V_{GS} = 10\text{ V}, V_{DS} \geq 2.0 V_{DS(on)}$)	$I_{D(on)}$	750	—	mAdc
Forward Transconductance ($V_{DS} \geq 2.0 V_{DS(on)}, I_D = 500\text{ mA}$)	g_{fs}	100	—	μmhos

1. Pulse Test: Pulse Width $\leq 300\text{ }\mu\text{s}$, Duty Cycle $\leq 2.0\%$.

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted) (Continued)

Characteristic	Symbol	Min	Max	Unit
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DYNAMIC CHARACTERISTICS

Input Capacitance	$(V_{DS} = 25 \text{ Vdc}, V_{GS} = 0, f = 1.0 \text{ MHz})$	C_{iss}	—	60	pF
Output Capacitance		C_{oss}	—	25	
Reverse Transfer Capacitance		C_{rss}	—	5.0	

SWITCHING CHARACTERISTICS(1)

Turn-On Delay Time	$(V_{DD} = 15 \text{ Vdc}, I_D = 600 \text{ mA}, R_{gen} = 25 \Omega, R_L = 23 \Omega)$	t_{on}	—	10	ns
Turn-Off Delay Time		t_{off}	—	10	

1. Pulse Test: Pulse Width $\leq 300 \text{ ms}$, Duty Cycle $\leq 10\%$.

RESISTIVE SWITCHING

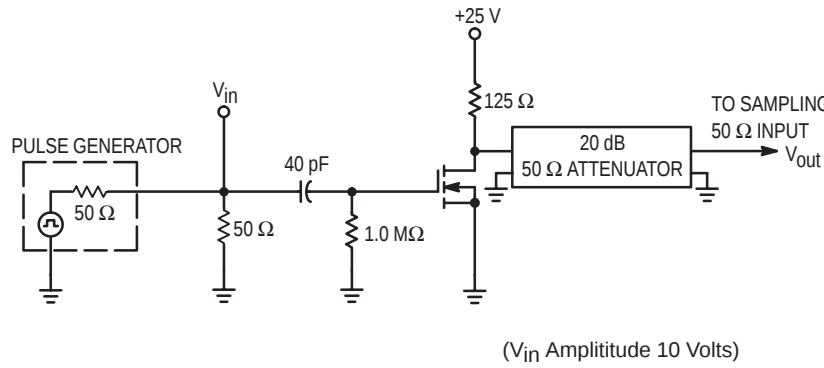


Figure 1. Switching Test Circuit

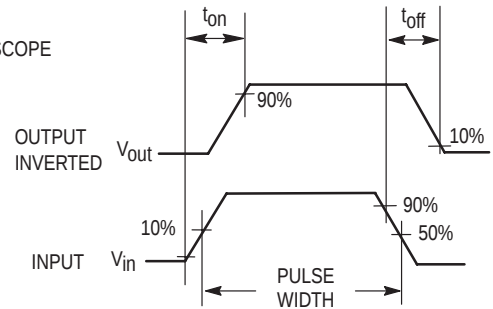


Figure 2. Switching Waveforms

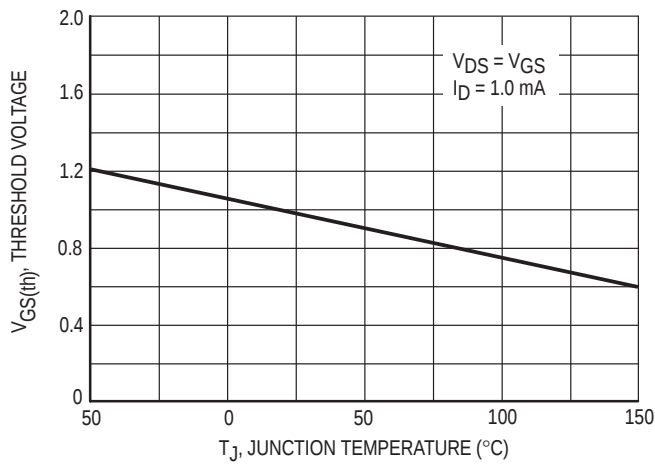


Figure 3. $V_{GS(th)}$ Normalized versus Temperature

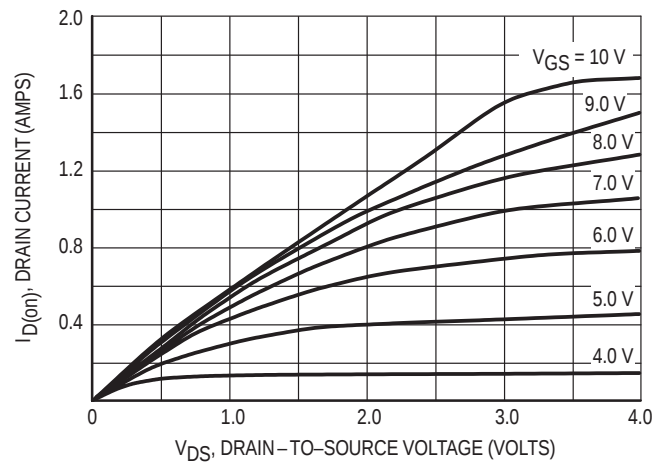


Figure 4. On-Region Characteristics

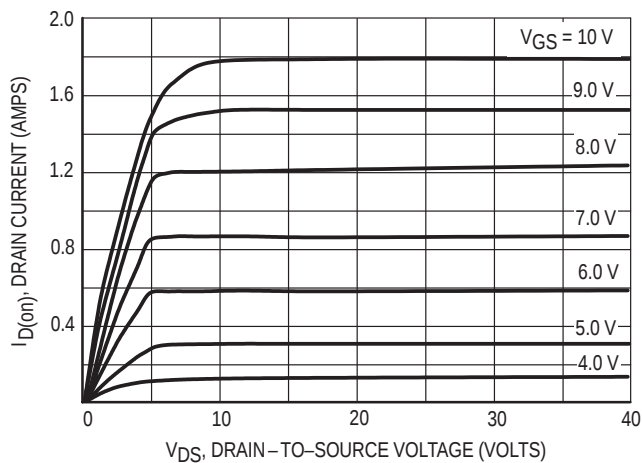


Figure 5. Output Characteristics

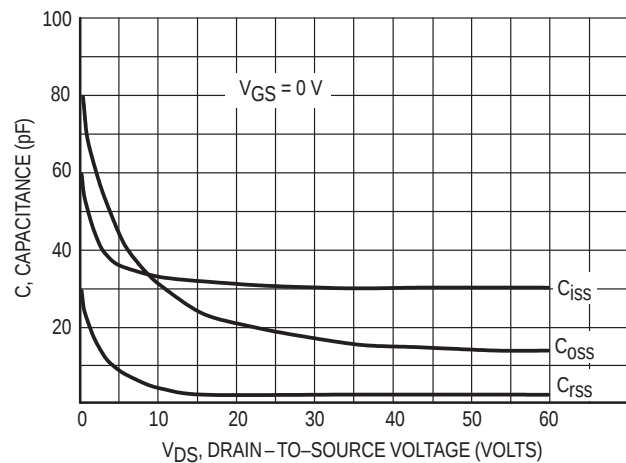


Figure 6. Capacitance versus Drain-To-Source Voltage